



# FDC021N30

## N-Channel PowerTrench<sup>®</sup> MOSFET 30 V, 6.1 A, 26 mΩ

### Features

- Max  $r_{DS(on)}$  = 26 mΩ at  $V_{GS} = 10$  V,  $I_D = 6.1$  A
- Max  $r_{DS(on)}$  = 33 mΩ at  $V_{GS} = 4.5$  V,  $I_D = 5.3$  A
- High Performance Trench Technology for Extremely Low  $r_{DS(on)}$
- High Power and Current Handling Capability in a Widely Used Surface Mount Package
- Fast Switching Speed
- RoHS Compliant

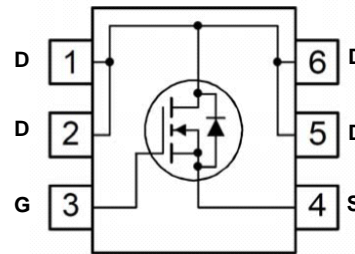
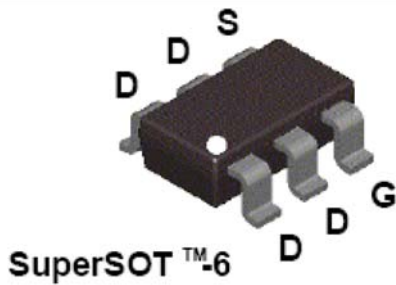


### General Description

This N-Channel PowerTrench MOSFET is produced using Fairchild's advanced PowerTrench<sup>®</sup> process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

### Applications

- Load Switch
- Battery Protection
- Power Management



### MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage (Note 3)	$\pm 20$	V
$I_D$	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	6.1	A
	-Pulsed (Note 4)	62	
$P_D$	Power Dissipation (Note 1a)	1.6	W
	Power Dissipation (Note 1b)	0.7	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to + 150	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	78	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	175	$^\circ\text{C/W}$

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
21N	FDC021N30	SSOT-6 <sup>TM</sup>	7"	8 mm	3000 units

**Electrical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
--------	-----------	-----------------	------	------	------	-------

**Off Characteristics**

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , referenced to $25^\circ\text{C}$		16		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , referenced to $25^\circ\text{C}$		-5		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.1 \text{ A}$		19	26	m $\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 5.3 \text{ A}$		23	33	
		$V_{GS} = 10 \text{ V}, I_D = 6.1 \text{ A}, T_J = 125^\circ\text{C}$		26	37	
$g_{FS}$	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_D = 6.1 \text{ A}$		30		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		510	710	pF
$C_{oss}$	Output Capacitance			170	240	pF
$C_{rss}$	Reverse Transfer Capacitance			22	30	pF
$R_g$	Gate Resistance		0.1	1.3	2.6	$\Omega$

**Switching Characteristics**

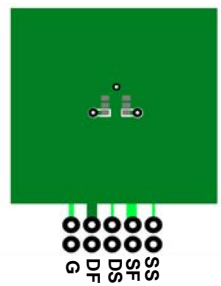
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15 \text{ V}, I_D = 6.1 \text{ A}, V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		6	12	ns	
$t_r$	Rise Time			2	10	ns	
$t_{d(off)}$	Turn-Off Delay Time			13	24	ns	
$t_f$	Fall Time			2	10	ns	
$Q_{g(TOT)}$	Total Gate Charge		$V_{GS} = 0 \text{ V to } 10 \text{ V}$		7.7	10.8	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$	$V_{DD} = 15 \text{ V}, I_D = 6.1 \text{ A}$		3.7	5.2	nC
$Q_{gs}$	Gate to Source Charge			1.4		nC	
$Q_{gd}$	Gate to Drain "Miller" Charge			1.1		nC	

**Drain-Source Diode Characteristics**

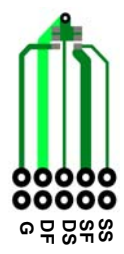
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 6.1 \text{ A}$ (Note 2)		0.8	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F = 6.1 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		14	25	ns
$Q_{rr}$	Reverse Recovery Charge			3	10	nC

**Notes:**

- 1:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



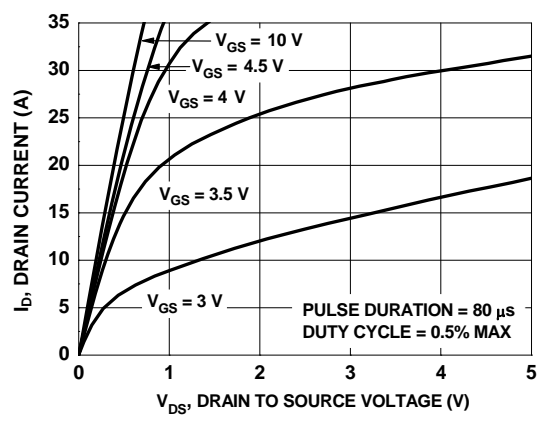
a. 78  $^\circ\text{C}/\text{W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



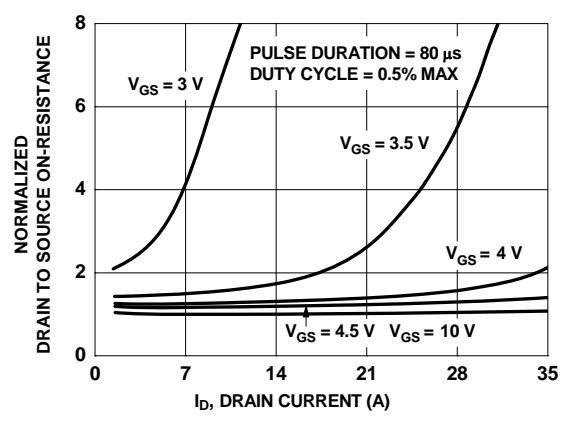
b. 175  $^\circ\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper

- 2: Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty Cycle < 2.0%.
- 3: As an N-ch device, the negative  $V_{GS}$  rating is for low duty cycle pulse occurrence only. No continuous rating is implied.
- 4: Pulsed  $I_D$  please refer to Fig 11 SOA graph for more details.

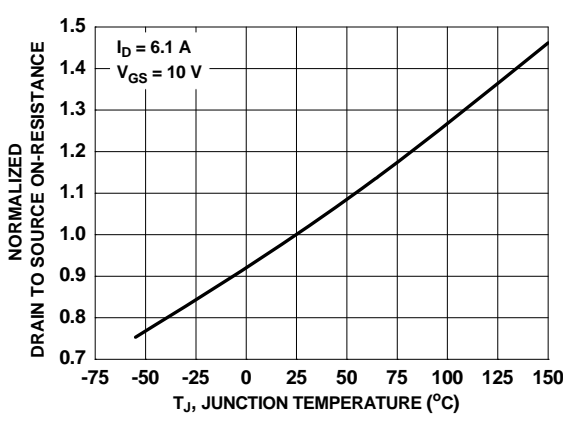
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted.



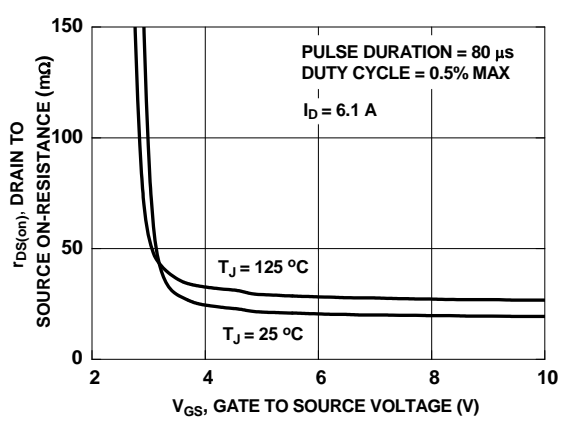
**Figure 1. On-Region Characteristics**



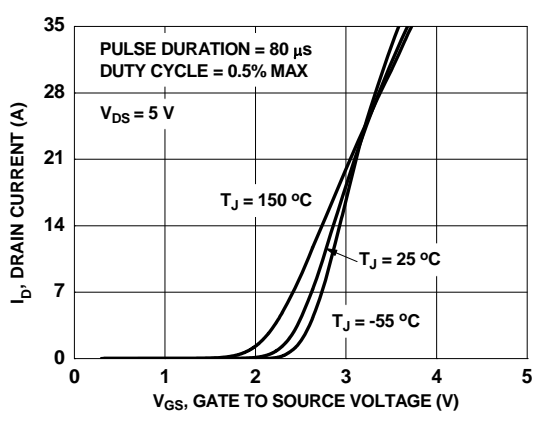
**Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage**



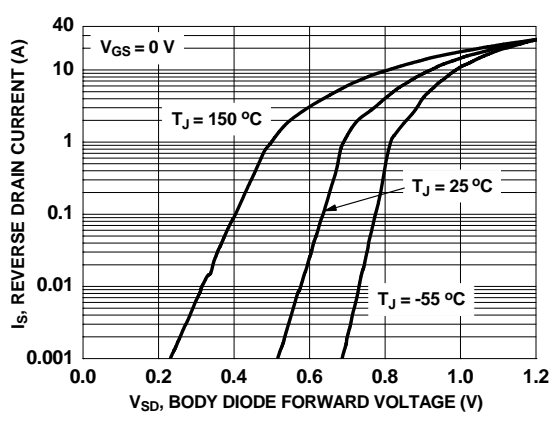
**Figure 3. Normalized On-Resistance vs. Junction Temperature**



**Figure 4. On-Resistance vs. Gate to Source Voltage**

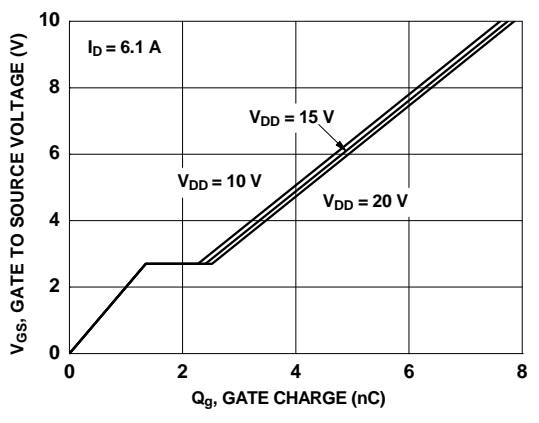


**Figure 5. Transfer Characteristics**

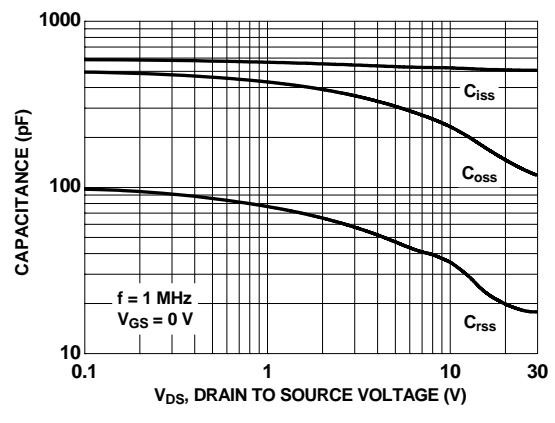


**Figure 6. Source to Drain Diode Forward Voltage vs. Source Current**

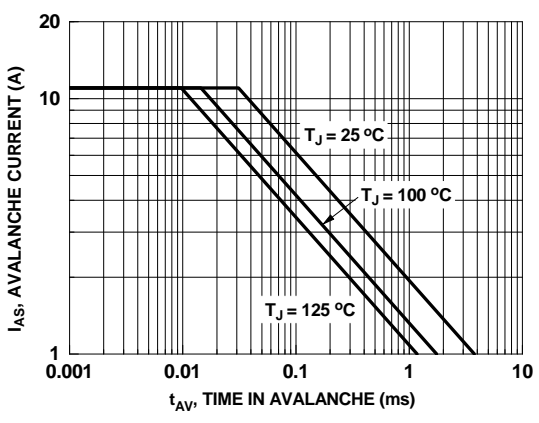
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted.



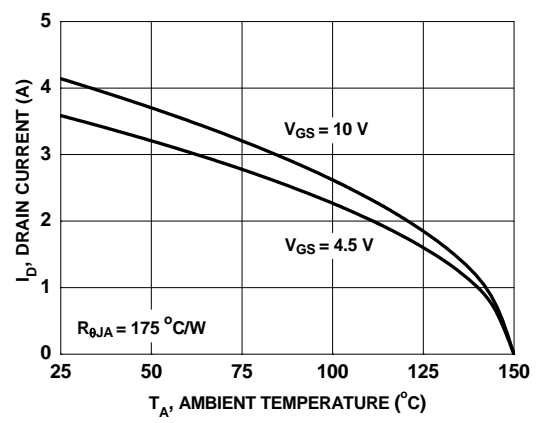
**Figure 7. Gate Charge Characteristics**



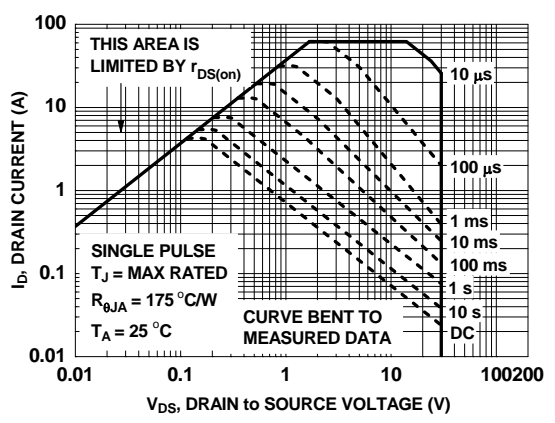
**Figure 8. Capacitance vs. Drain to Source Voltage**



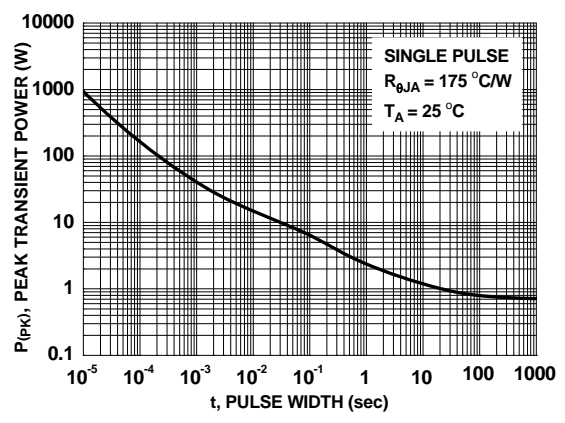
**Figure 9. Unclamped Inductive Switching Capability**



**Figure 10. Maximum Continuous Drain Current vs. Ambient Temperature**

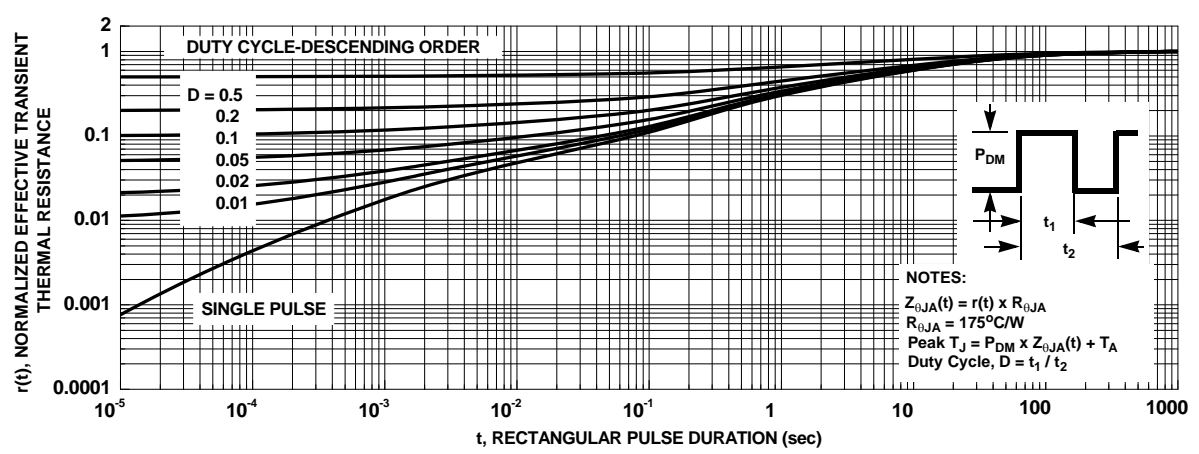


**Figure 11. Forward Bias Safe Operating Area**



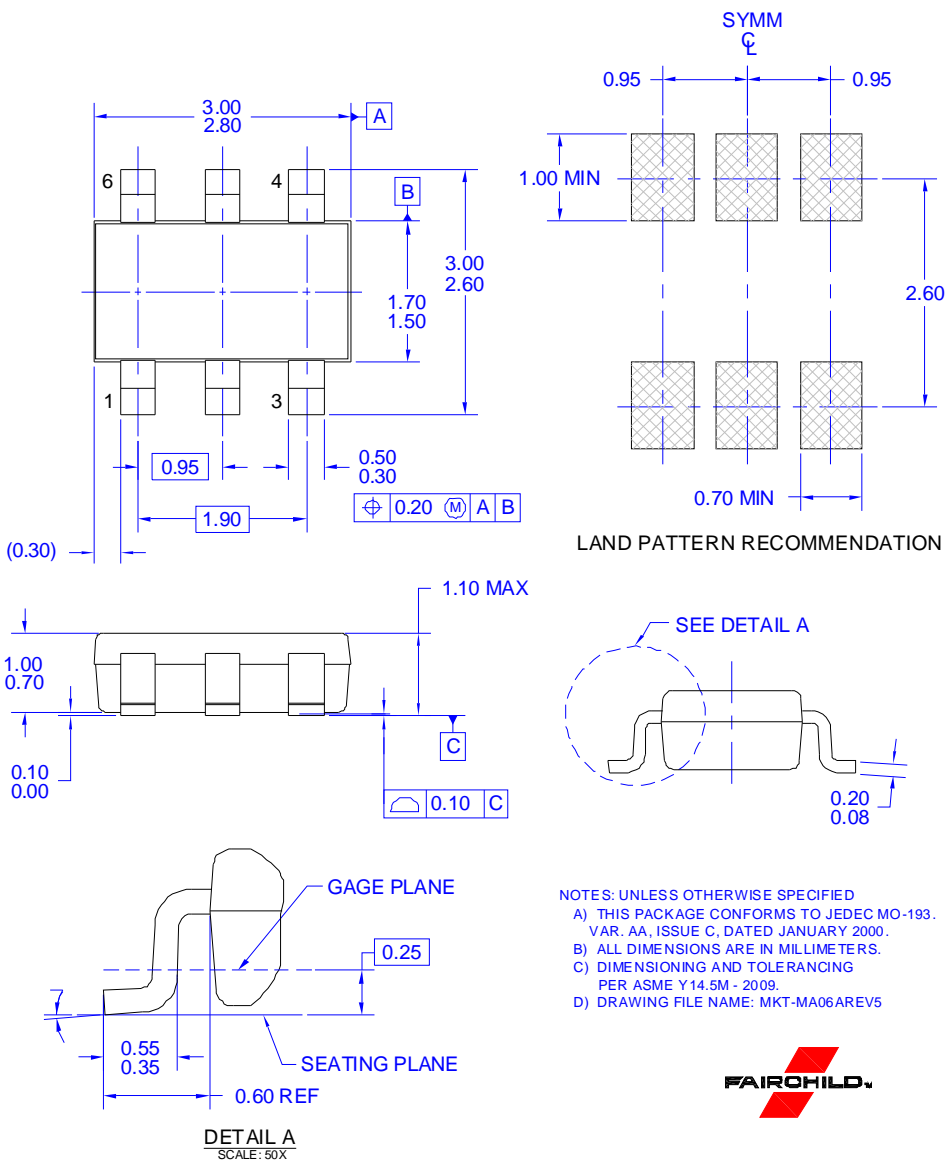
**Figure 12. Single Pulse Maximum Power Dissipation**

**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted.



**Figure 13. Junction-to-Ambient Transient Thermal Response Curve**

### Dimensional Outline and Pad Layout








Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.



**TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- |   |   |   |   |
|---|---|---|---|
| AccuPower™  | F-PFS™  | OPTOPLANAR®   |  |
| AttitudeEngine™   | FRFET®  |  | TinyBoost®  |
| Awinda®   | Global Power ResourceSM                         | PowerTrench®  | TinyBuck®   |
| AX-CAP®*  | GreenBridge™                                    | PowerXST™   | TinyCalc™   |
| BitSiC™   | Green FPS™                                      | Programmable Active Droop™  | TinyLogic®  |
| Build it Now™   | Green FPS™ e-Series™                            | QFET®   | TINYOPTO™   |
| CorePLUS™   | Gmax™   | QS™   | TinyPower™  |
| CorePOWER™  | GTO™  | Quiet Series™   | TinyPWM™  |
| CROSSVOLT™  | IntelliMAX™                                     | RapidConfigure™   | TinyWire™   |
| CTL™  | ISOPLANAR™                                      |  | TranSiC™  |
| Current Transfer Logic™   | Marking Small Speakers Sound Louder and Better™ | SignalWise™   | TriFault Detect™  |
| DEUXPEED®   | MegaBuck™                                       | SmartMax™   | TRUECURRENT®*   |
| Dual Cool™  | MICROCOUPLER™                                   | SMART START™  | μSerDes™  |
| EcoSPARK®   | MicroFET™                                       | Solutions for Your Success™   |  |
| EfficientMax™   | MicroPak™                                       | SPM®  | UHC®  |
| ESBC™   | MicroPak2™                                      | STEALTH™  | Ultra FRFET™  |
|  | MillerDrive™                                    | SuperFET®   | UniFET™   |
| Fairchild®  | MotionMax™                                      | SuperSOT™-3   | VCX™  |
| Fairchild Semiconductor®  | MotionGrid®                                     | SuperSOT™-6   | VisualMax™  |
| FACT Quiet Series™  | MTi®  | SuperSOT™-8   | VoltagePlus™  |
| FACT®   | MTx®  | SupreMOS®   | XST™  |
| FastvCore™  | MVN®  | SyncFET™  | Xsens™  |
| FETBench™   | mWSaver®  | Sync-Lock™  | 仙童®   |
| FPS™  | OptoHi™   |   |   |
|   | OPTOLOGIC®                                      |   |   |

\*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

**DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT [HTTP://WWW.FAIRCHILDSEMI.COM](http://www.fairchildsemi.com). FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

**AUTHORIZED USE**

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

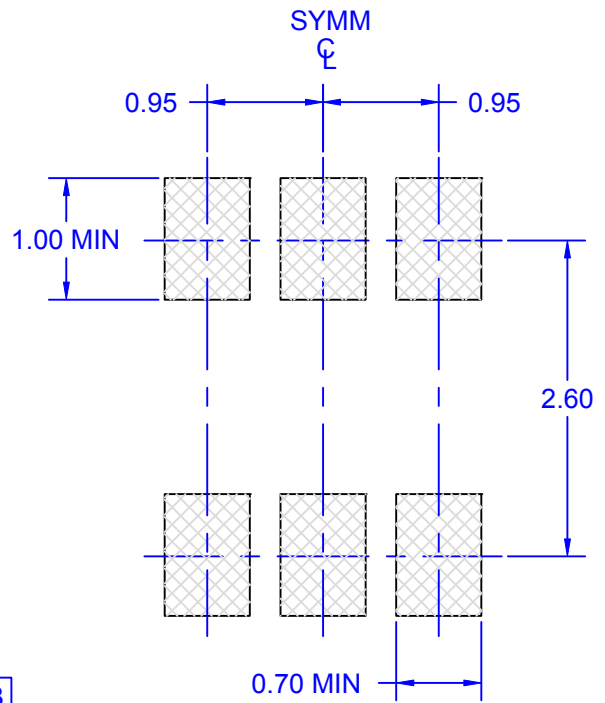
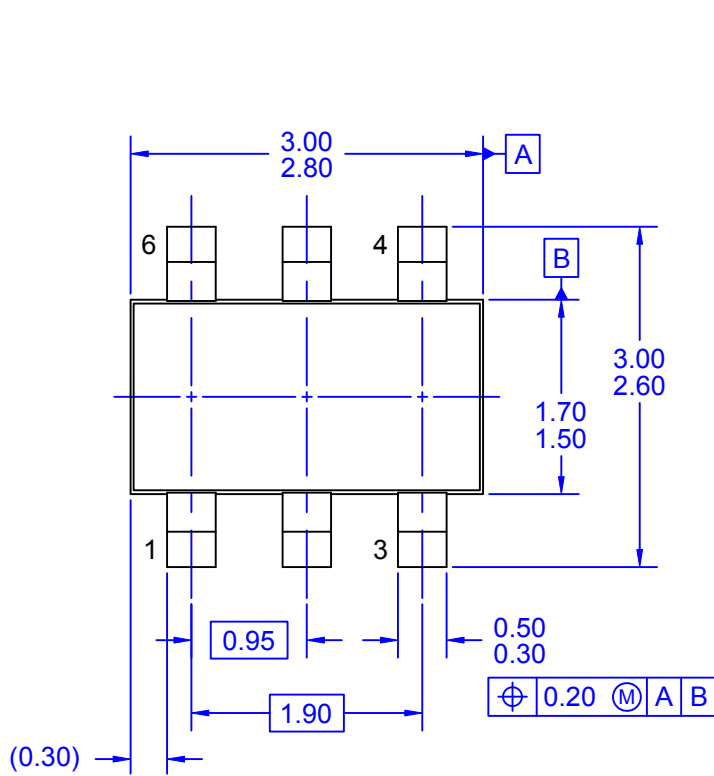
**ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, [www.fairchildsemi.com](http://www.fairchildsemi.com), under Terms of Use. Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

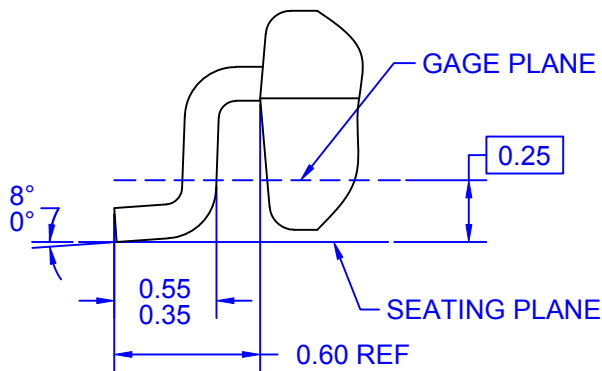
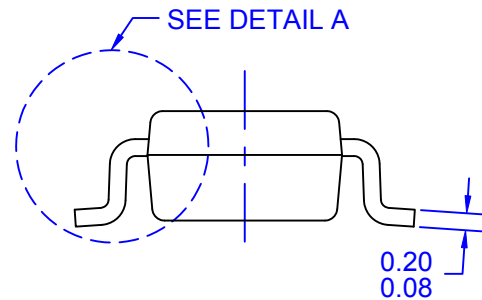
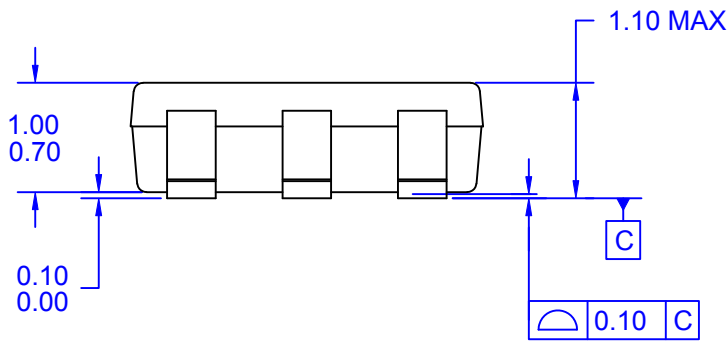
**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.



LAND PATTERN RECOMMENDATION



DETAIL A  
SCALE: 50X

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 2009.
  - D) DRAWING FILE NAME: MKT-MA06AREV5







**TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- |                          |  |                                       |                  |
|--------------------------|--|---------------------------------------|------------------|
| AccuPower™               | F-PFS™   | OPTOPLANAR®                           | SYSTEM GENERAL®  |
| AttitudeEngine™          | FRFET®   | Power Supply WebDesigner™             | TinyBoost®       |
| Awinda®                  | Global Power Resource <sup>SM</sup>            | PowerTrench®                          | TinyBuck®        |
| AX-CAP®*                 | GreenBridge™                                   | PowerXS™                              | TinyCalc™        |
| BitSiC™                  | Green FPS™                                     | Programmable Active Droop™            | TinyLogic®       |
| Build it Now™            | Green FPS™ e-Series™                           | QFET®                                 | TINYOPTO™        |
| CorePLUS™                | Gmax™  | QS™                                   | TinyPower™       |
| CorePOWER™               | GTO™   | Quiet Series™                         | TinyPWM™         |
| CROSSVOL™                | IntelliMAX™                                    | RapidConfigure™                       | TinyWire™        |
| CTL™                     | ISOPLANAR™                                     | Saving our world, 1mW/W/kW at a time™ | TranSiC™         |
| Current Transfer Logic™  | Making Small Speakers Sound Louder and Better™ | SignalWise™                           | TriFault Detect™ |
| DEUXPEED®                | MegaBuck™                                      | SmartMax™                             | TRUECURRENT®*    |
| Dual Cool™               | MICROCOUPLER™                                  | SMART START™                          | μSerDes™         |
| EcoSPARK®                | MicroFET™                                      | Solutions for Your Success™           | UHC®             |
| EfficientMax™            | MicroPak™                                      | SPM®                                  | Ultra FRFET™     |
| ESBC™                    | MicroPak2™                                     | STEALTH™                              | UniFET™          |
| F <sup>®</sup>           | MillerDrive™                                   | SuperFET®                             | VCX™             |
| Fairchild®               | MotionMax™                                     | SuperSOT™-3                           | VisualMax™       |
| Fairchild Semiconductor® | MotionGrid®                                    | SuperSOT™-6                           | VoltagePlus™     |
| FACT Quiet Series™       | MTi®   | SuperSOT™-8                           | XST™             |
| FACT®                    | MTx®   | SupreMOS®                             | Xsens™           |
| FastvCore™               | MVN®   | SyncFET™                              | 仙童®              |
| FETBench™                | mWSaver®                                       | Sync-Lock™                            |                  |
| FPS™                     | OptoHiT™                                       |                                       |                  |
|                          | OPTOLOGIC®                                     |                                       |                  |

\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

**DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT [HTTP://WWW.FAIRCHILDSEMI.COM](http://www.fairchildsemi.com). FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

**AUTHORIZED USE**

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

**ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, [www.fairchildsemi.com](http://www.fairchildsemi.com), under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I77

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Fairchild Semiconductor:](#)

[FDC021N30](#)